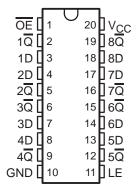
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

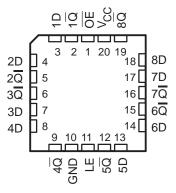
These octal transparent D-type latches with 3-state outputs are designed specifically for drivina highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

When the latch-enable (LE) input is high, the Q outputs follow the complements of the data (D) inputs. When LE is taken low, the \overline{Q} outputs are latched at the inverse of the levels at the D inputs.

SN54ABT533 . . . J OR W PACKAGE SN74ABT533A...DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT533 . . . FK PACKAGE (TOP VIEW)



A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT533 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT533A is characterized for operation from -40°C to 85°C.



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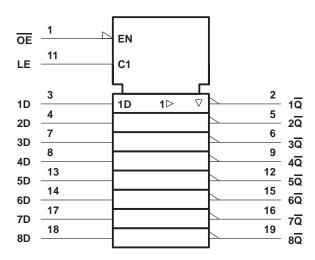
EPIC-IIB is a trademark of Texas Instruments Incorporated



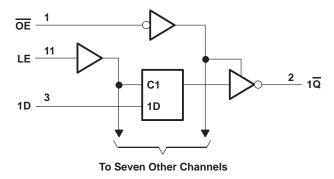
FUNCTION TABLE (each latch)

	INPUTS									
OE	LE	D	OU <u>TP</u> UT Q							
L	Н	Н	L							
L	Н	L	Н							
L	L	Χ	\overline{Q}_0							
Н	X	Χ	Z							

logic symbol†



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Voltage range applied to any output in the high	or power-off state, V _O	
Current into any output in the low state, IO: SN	54ABT533	96 mA
SN	74ABT533A	
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, I_{OK} ($V_O < 0$)		
Package thermal impedance, θ _{JA} (see Note 2):	DB package	115°C/W
	DW package	97°C/W
	N package	67°C/W
	PW package	
Storage temperature range, T _{stq}		

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54A	BT533	SN74AB	T533A	UNIT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
loh	High-level output current		-24		-32	mA
loL	Low-level output current		48		64	mA
Δt/Δν	Input transition rise or fall rate		10		10	ns/V
TA	Operating free-air temperature	– 55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEST CONDITIO	Me	T	_A = 25°C	;	SN54A	BT533	SN74AB	T533A	UNIT
PARAMETER		ONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	/, I _I = −18 mA				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	IOH = -3 mA		2.5			2.5		2.5		
\/	V _C C = 5 V,	IOH = -3 mA		3			3		3		V
VOH	V _{CC} = 4.5 V	I _{OH} = -24 mA		2			2				V
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2		
Vai	V00 - 4 5 V	I _{OL} = 48 mA				0.55		0.55			V
VOL	V _{CC} = 4.5 V	I _{OL} = 64 mA				0.55*				0.55	V
V _{hys}					100						mV
ΙΙ	$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GN	ND			±1		±1		±1	μΑ
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V				10		10		10	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V				-10		-10		-10	μΑ
l _{off}	$V_{CC} = 0$,	V _I or V _O ≤ 4.5 \	J			±150				±150	μΑ
ICEX	$V_{CC} = 5.5 V$,	V _O = 5.5 V	Outputs high			50		50		50	μΑ
IO [‡]	$V_{CC} = 5.5 V$,	V _O = 2.5 V		-50	-140	-180	-50	-180	-50	-180	mA
		_	Outputs high		1	250		250		250	μΑ
ICC	V _{CC} = 5.5 V, I _C V _I = V _{CC} or GI	•	Outputs low		24	30		30		30	mA
	1 1 2 1 2 1 2 1	1 D	Outputs disabled		0.5	250		250		250	μΑ
	V _{CC} = 5.5 V,		Outputs high			1.5		1.5		1.5	
ΔICC§	One input at 3.	One input at 3.4 V,				1.5		1.5		1.5	mA
	Other inputs at	V _{CC} or GND	Outputs disabled			1.5		1.5		1.5	
Ci	$V_{I} = 2.5 \text{ V or } 0.$	= 2.5 V or 0.5 V			3.5						pF
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			6.5						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT533, SN74ABT533A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS186D - JANUARY 1991 - REVISED JANUARY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54A	BT533		
			V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
t _W	Pulse duration, LE high		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	High or low	2.1		2.1		ns
t _h	Hold time, data after LE↓	High or low	1.5		1.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN74AE	3T533A		
			V _{CC} :	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
t _W	Pulse duration, LE high		3.3		3.3		ns
t _{su}	Setup time, data before LE↓	High or low	2.1		2.1		ns
th	Hold time, data after LE↓	High or low	2.1		2.1		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

				SN	54ABT5	33		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 \ 4 = 25°C	/, }	MIN	MAX	UNIT
			MIN	TYP	MAX			
tpLH	D	Q	1.9	4.2	5.4	1.9	6.7	ns
t _{PHL}	В	Q	3.1	4.9	6.3	3.1	6.9	115
tpLH	1.5	Q	2.7	4.9	6.2	2.7	7.6	ns
t _{PHL}	LE	Q	3.5	5.4	6.8	3.5	7.5	115
^t PZH	ŌĒ	Q	1.6	3.7	4.8	1.6	5.8	ns
tPZL	OE .	Q	2.4	4.2	6.2	2.4	6.9	115
t _{PHZ}	ŌĒ	Q	2.8	5.1	6.2	2.8	7.2	ne
t _{PLZ}	UE UE	l Q	2	4.1	6	2	6.9	ns

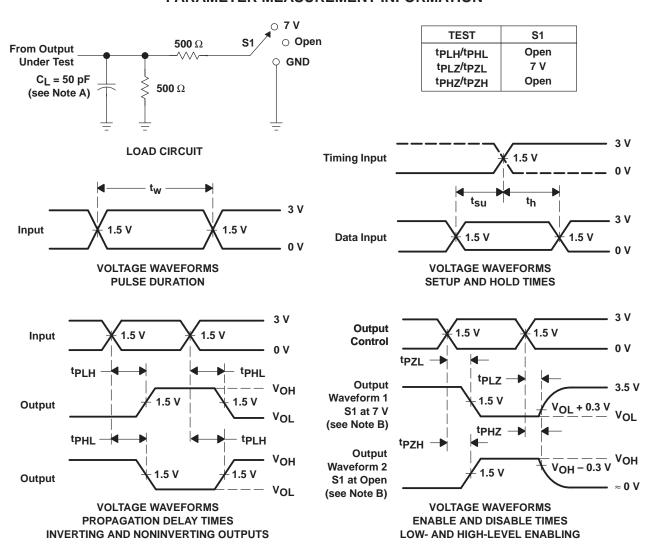
SN54ABT533, SN74ABT533A OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS186D - JANUARY 1991 - REVISED JANUARY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN7	4ABT53	3A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	D	Q	1.7	4.2	5.4	1.7	6.4	ns
t _{PHL}	В	Q Q	2.6	4.9	6.3	2.6	6.6	115
t _{PLH}		Q		4.9	6.2	2.7	7.3	20
t _{PHL}	LE		3.5	5.4	6.8	3.5	7.3	ns
^t PZH	ŌĒ	Ē Q		3.7	4.8	1.6	5.7	20
tPZL	OE .	Q	2.4	4.2	6.2	2.4	6.7	ns
^t PHZ	ŌĒ	Q	1.6	5.1	6.2	1.6	6.9	ns
tPLZ	J ∪E		2	4.1	6	2	6.5	115

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9584301Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9584301Q2A SNJ54 ABT533FK	Samples
5962-9584301QRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9584301QR A SNJ54ABT533J	Samples
SN74ABT533AN	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT533AN	Samples
SN74ABT533APWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB533A	Samples
SNJ54ABT533FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9584301Q2A SNJ54 ABT533FK	Samples
SNJ54ABT533J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9584301QR A SNJ54ABT533J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

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(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT533APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74ABT533APWR	TSSOP	PW	20	2000	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9584301Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74ABT533AN	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ABT533FK	FK	LCCC	20	55	506.98	12.06	2030	NA

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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